

Thermal Putty Gel / XK-G50

Introduction

Syringes packaging, automated production, high temperature resistance, non-corrosive to metal, 100% thermal curing putty. XK-G series is silicone based, high performance thermal Gel, filling with a variety of high performance ceramic powder, having the features of high thermal conductivity, low thermal, good insulation and infinite compression.

Features

- Excellent compressibility
- Very low thermal resistance
- Good creep performance
- Best for north bridge IC



Applications

- Consumer electronics / Automotive Systems
- Telecommunications / Hand set applications

	Unit	XK-G50	Method
Color		White	visual
Flow Rate (30cc EFD cartridges 0.100" orifice 90psi)	g/min	6	
Specific Gravity	g/cm ³	3.3	ASTM D792
Volume Resistivity	Ωcm	>10 ¹³	ASTM D257
Thermal Conductivity	W/mK	5	HOT DISK
Breakdown Voltage	KV/mm	10	ASTM D149
Dielectric Constant	1	8	ASTM D150
Low Limit BLT Thickness	mm	0.08	ASTM D374
Application temperature	°C	-50~200	
Shelf life	month	12	
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Coefficient of Thermal Expansion	ppm/K	140	
Flammability	UL94	V-0	UL94